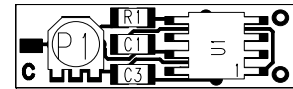


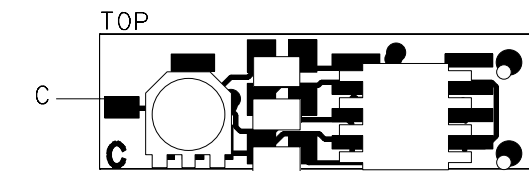
### ORDERING INFORMATION

Type	Package	Options	Order Designation
iC-WK	BMST WK2D	none	iCSY WK2D

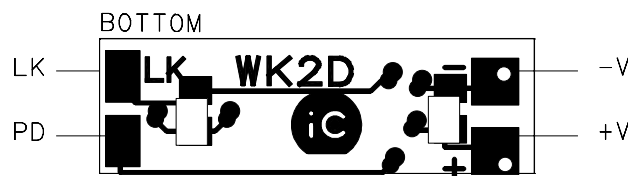


20mm x 6.25mm

### PIN CONFIGURATION PIN FUNCTIONS



No.	Name	Function
1	+V	+5V Supply Voltage
2	-V	Ground
3	LK	Laserdiode Kathode
4	PD	Photodiode
5	C	Common Pin Laserdiode



### ABSOLUTE MAXIMUM RATINGS

Item	Symbol	Parameter	Conditions	Fig.	Min. Typ. Max.			Unit
TG1	Ta	Operating Ambient Temperature Range (extended temperature range on request)			0		50	°C
TG2	Ts	Storage Temperature Range			-20		70	°C

# iC-WK BMST WK2D

## PACKAGE SPECIFICATION



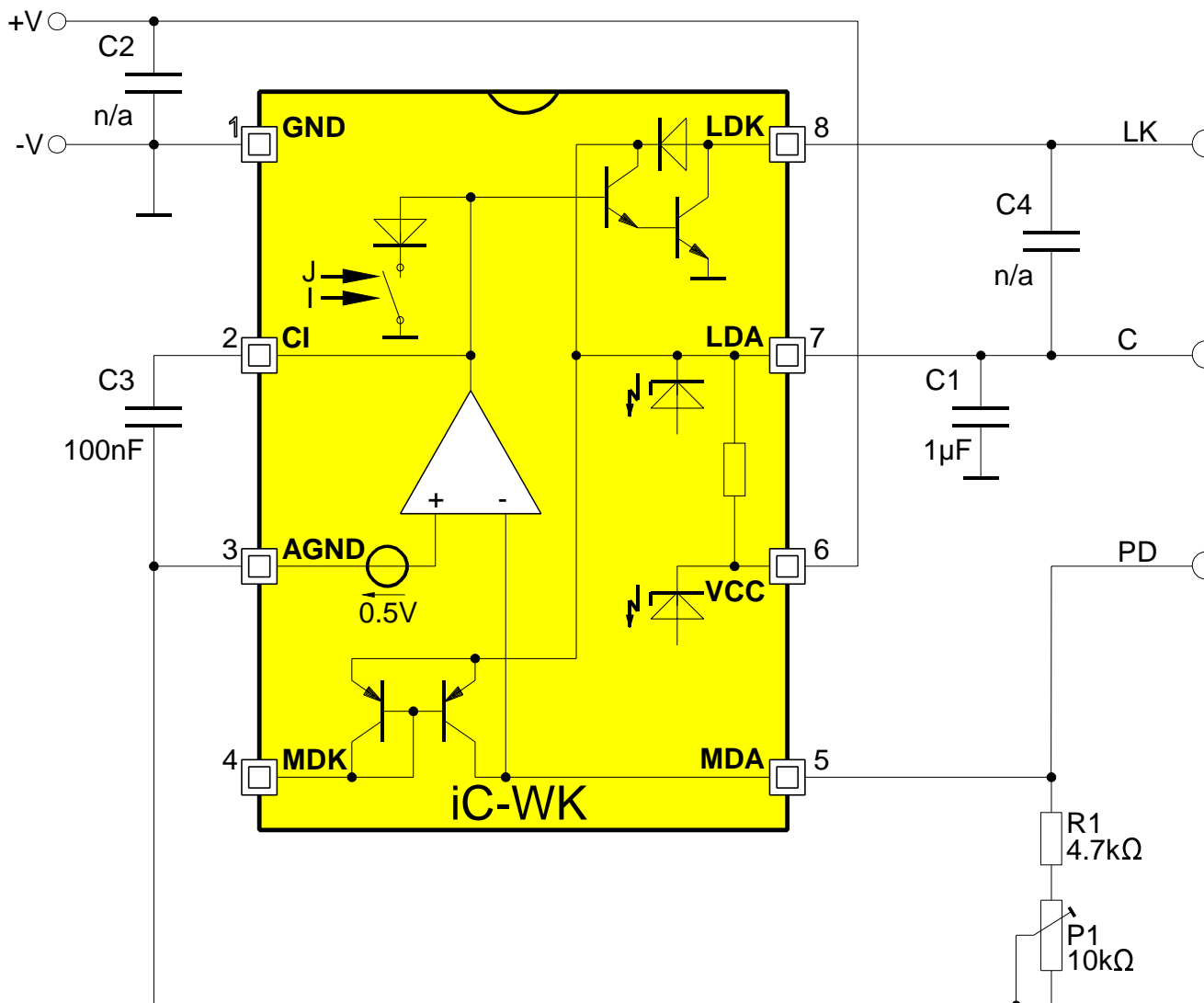
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### BASIC ELECTRICAL CHARACTERISTICS

Operating Conditions  $V_{CC} = 5V \pm 5\%$ ,  $T_j = -0..50^\circ\text{C}$ , unless otherwise noted

Item	Symbol	Parameter	Conditions	T <sub>j</sub> °C	Fig.	Min.	Typ.	Max.	Unit
<b>Total Device</b>									
001	VDD	Permissible Supply Voltage				2.4		5.5	V
002	I(VDD)	Supply Current in VDD	closed control loop, I(PD)= 0, RM= 200Ω, I(LA)= 70mA	27				5.5	mA
003	ton()	Power On Delay	VCC: 0V-5V to 95% I(LD); I(LD)= 70mA, CI= 47nF I(LD)= 70mA, CI= 100nF	27				70 150	μs μs

### SCHEMATIC DIAGRAM



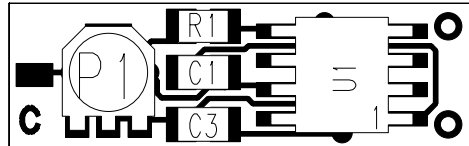
# iC-WK BMST WK2D

## PACKAGE SPECIFICATION

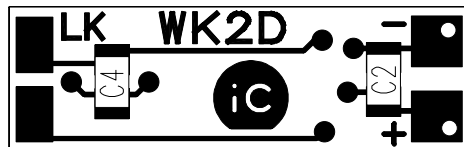
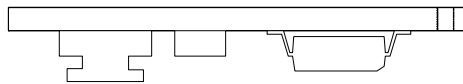


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### DEVICE ASSEMBLY



TOP



BOTTOM

dra\_wk2d\_pack\_assy

### ASSEMBLY PART LIST

Item	Name	Device	Type/Value	Tolerance	Material	Comments	Package	Place-ment
01	U1	Laser Driver	iC-WK				SO8	TOP
04	R1	Resistor	4.7k	1%			RSMD0805	TOP
05	C1	Capacitor	1 $\mu$ F	10%			CSMD0805	TOP
06	C2	Capacitor	n. a.				CSMD0805	BOT
07	C3	Capacitor	100nF	20%			CSMD0805	TOP
08	C4	Capacitor	n. a.				CSMD0805	BOT
15	P1	Trimmer	10k	25%			meggit Typ 3165	TOP

Germany and other countries: LASER COMPONENTS GmbH, Phone: +49 8142 2864 0, Fax: +49 8142 2864 11, info@lasercomponents.com

USA: LASER COMPONENTS IG, Inc., Phone: +1 603 821 7040, Fax: +1 603 821 7041, info@laser-components.com

Great Britain: LASER COMPONENTS (UK) Ltd., Phone: +44 1245 491 499, Fax: +44 1245 491 801, info@lasercomponents.co.uk

France: OPTOPHOTONICS sa, Phone: +33 1 3959 5225, Fax: +33 1 3959 5350, info@optophotonics.fr

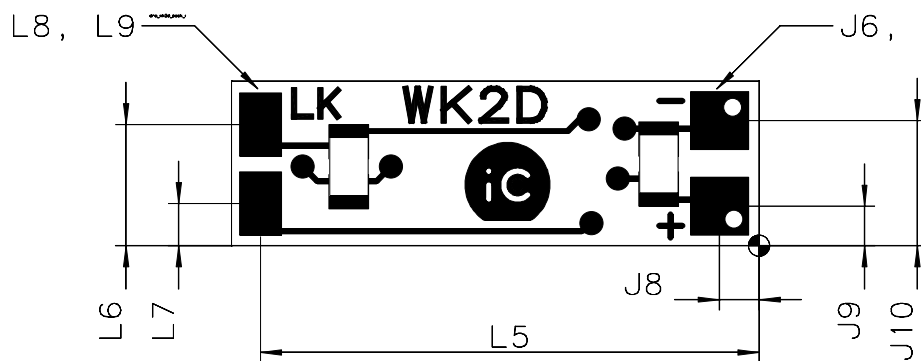
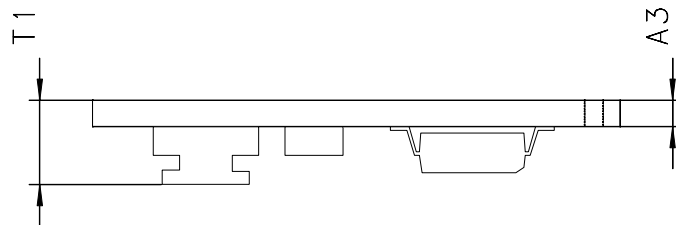
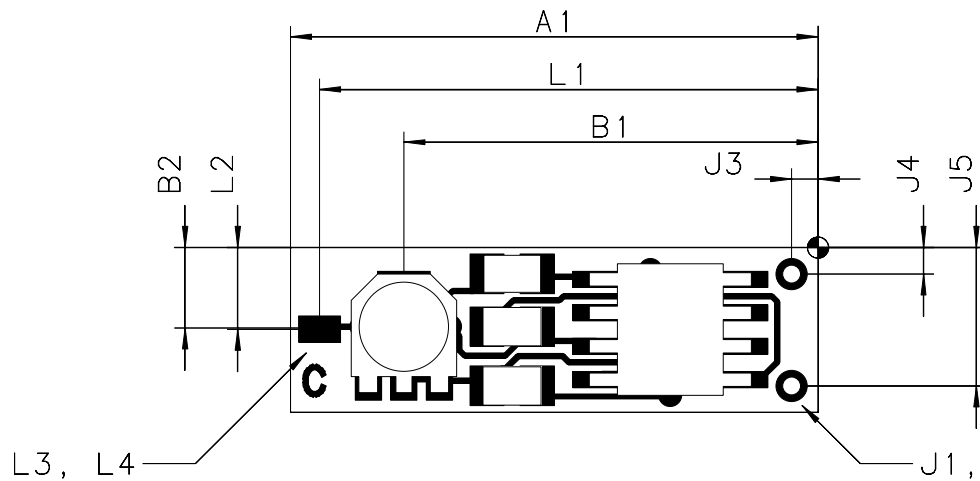
# iC-WK BMST WK2D

## PACKAGE SPECIFICATION



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### PHYSICAL DIMENSIONS (given in mm)



# iC-WK BMST WK2D

## PACKAGE SPECIFICATION



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### DIMENSION TABLE

Item	Parameter	Comments					Unit
			Min.	Typ.	Max.	Tolerance	
	<b>Substrate</b>						
A1	Outline X			20.00		± 0.4	mm
A2	Outline Y			6.25		± 0.15	mm
A3	Substrate Thickness (incl CU and Solder Stop)		0.9		1.1		mm
	<b>Trimmer Placement</b>						
B1	Trimmer Position vs. Reference X	Axis of Trimmer		15.7		± 0.6	mm
B2	Trimmer Position vs. Reference Y	Axis of Trimmer		3.0		± 0.6	mm
	<b>Power Connector</b>						
J1	Drill Diameter			0.7		-0 / +0.1	mm
J2	Pad Diameter			1.2		± 0.05	mm
J3	Drill Position vs. Reference X (-V, +V)			1.0		± 0.3	mm
J4	Drill Position vs. Reference Y (+V)			1.0		± 0.15	mm
J5	Drill Position vs. Reference Y (-V)			5.25		± 0.15	mm
J6	Pad Size X (-V,+V)			2.2		± 0.05	mm
J7	Pad Size Y (-V,+V)			2.2		± 0.05	mm
J8	Center Pad vs. Reference X (-V, +V)			1.5		± 0.3	mm
J9	Center Pad vs. Reference Y (+V)			1.5		± 0.15	mm
J10	Center Pad vs. Reference Y (-V)			4.75		± 0.15	mm
	<b>Laser Connector</b>						
L1	Center Pad vs. Reference X (Common Pin)			18.8		± 0.3	mm
L2	Center Pad vs. Reference Y (Common Pin)			3.1		± 0.15	mm
L3	Pad Size X (Common Pin)			1.6		± 0.05	mm
L4	Pad Size Y (Common Pin)			1.0		± 0.05	mm
L5	Center Pad vs. Reference X (LA, PD)			18.8		± 0.3	mm
L6	Center Pad vs. Reference Y (LA)			4.6		± 0.15	mm
L7	Center Pad vs. Reference Y (PD)			1.6		± 0.15	mm
L8	Pad Size X (LA, PD)			1.6		± 0.05	mm
L9	Pad Size Y (LA, PH)			2.4		± 0.05	mm
	<b>Thickness</b>						
T1	Overall Thickness		3.1				mm

# iC-WK BMST WK2D

## PACKAGE SPECIFICATION



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### REVISION HISTORY

Rev	Notes	Pages affected
A0	Initial version	all

### GENERAL HANDLING INSTRUCTIONS

Board micro system modules are not subject to dry pack delivery and are not intended for reflow soldering.

This specification is for a newly developed product. iC-Haus therefore reserves the right to modify data without further notice. Please contact us to ascertain the current data. The data specified is intended solely for the purpose of product description and is not to be deemed guaranteed in a legal sense. Any claims for damage against us - regardless of the legal basis - are excluded unless we are guilty of premeditation or gross negligence.

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